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Part Number: [0782793002](#)
Status: **Active**
Description: 0.60mm (.024") Pitch DDR3 SODIMM Socket, Right Angle, Reverse Mount, 5.20mm (.205") Mount Height, 204 Circuits, Lead Free

Documents:

[3D Model](#) [Product Specification PS-78279-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [78279](#)
 Component Type Socket
 JEDEC Outline N/A
 Product Name DDR3 S.O. DIMM

Physical

Circuits (Loaded) 204
 Circuits (maximum) 204
 Color - Resin Black
 Durability (mating cycles max) 25
 Entry Angle 25° Angle
 Flammability 94V-0
 Keying to Mating Part Yes
 Material - Plating Mating Gold
 Material - Plating Termination Gold
 Material - Resin High Temperature Thermoplastic
 PCB Locator Yes
 PCB Retention Yes
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.024 In
 Pitch - Mating Interface (mm) 0.60 mm
 Pitch - Term. Interface (in) 0.024 In
 Pitch - Term. Interface (mm) 0.60 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.76
 Plating min: Termination (µin) 2
 Plating min: Termination (µm) 0.05
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Surface Mount

Electrical

Current - Maximum per Contact 0.6A
 Voltage - Maximum 25V AC

Solder Process Data

Duration at Max. Process Temperature (seconds) 20
 Lead-free Process Capability Reflow Capable (SMT only)
 Max. Cycles at Max. Process Temperature 2
 Process Temperature max. C 260

Material Info

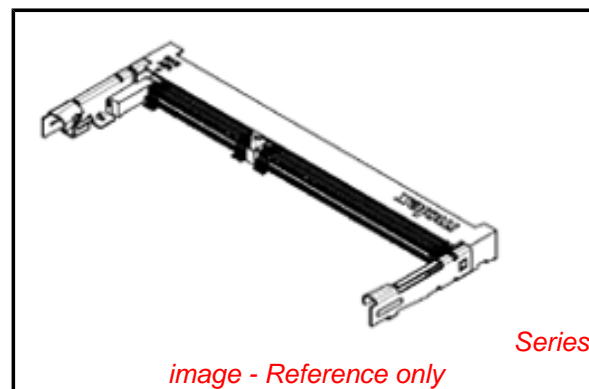


image - Reference only

EU RoHS

**ELV and RoHS
 Compliant**
**REACH SVHC
 Contains SVHC: No**
**Halogen-Free
 Status**

China RoHS



**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of
 Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
 non-product compliance questions.

Search Parts in this Series

[78279Series](#)

Mates With

JEDEC Standard Memory Modules

Reference - Drawing Numbers

Packaging Specification

Product Specification

Sales Drawing

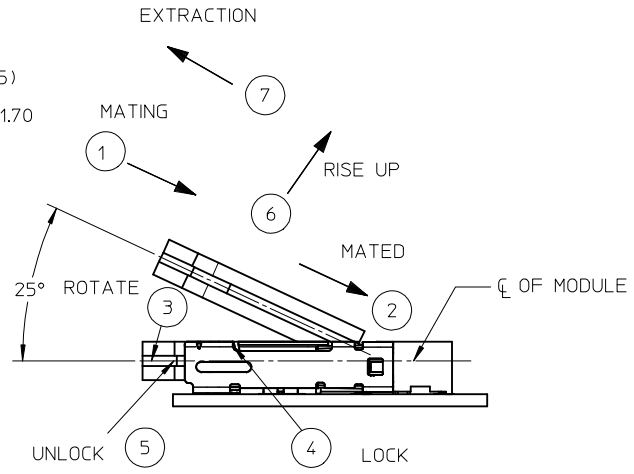
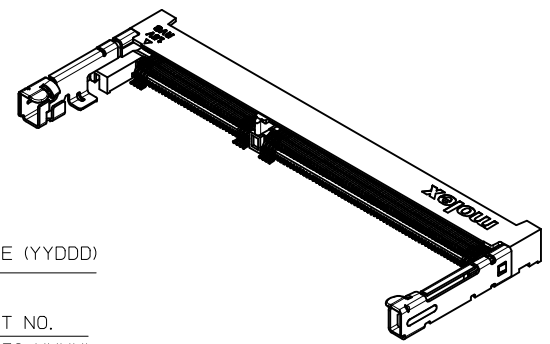
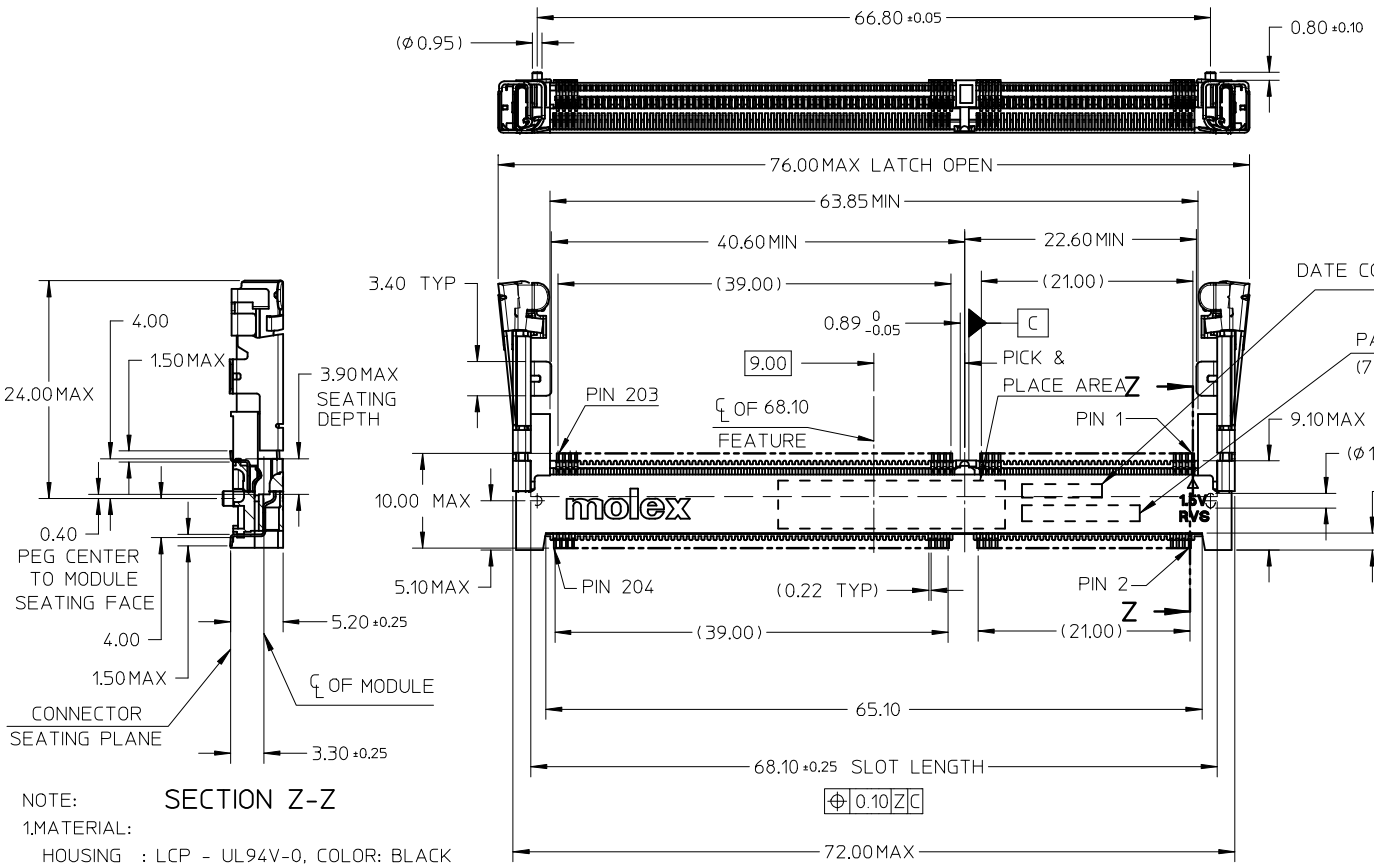
PK-78279-001

PS-78279-001

SD-78279-001

This document was generated on 05/10/2010

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SECTION Z-Z

NOTE:
 1.MATERIAL:
 HOUSING : LCP - UL94V-0, COLOR: BLACK
 CONTACTS : COPPER ALLOY
 LOCK LEVER : STAINLESS STEEL

2.FINISHES:
 CONTACT AREA : REFER TABLE IN SHEET 6.
 SOLDER TAIL AREA : REFER TABLE IN SHEET 6.
 LOCK LEVER SOLDER PAD : 100 MICRINCH / 2.54 MICROMETER MATTE TIN OVER 50 MICRINCH / 1.27 MICROMETER NICKEL.

3.RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-268

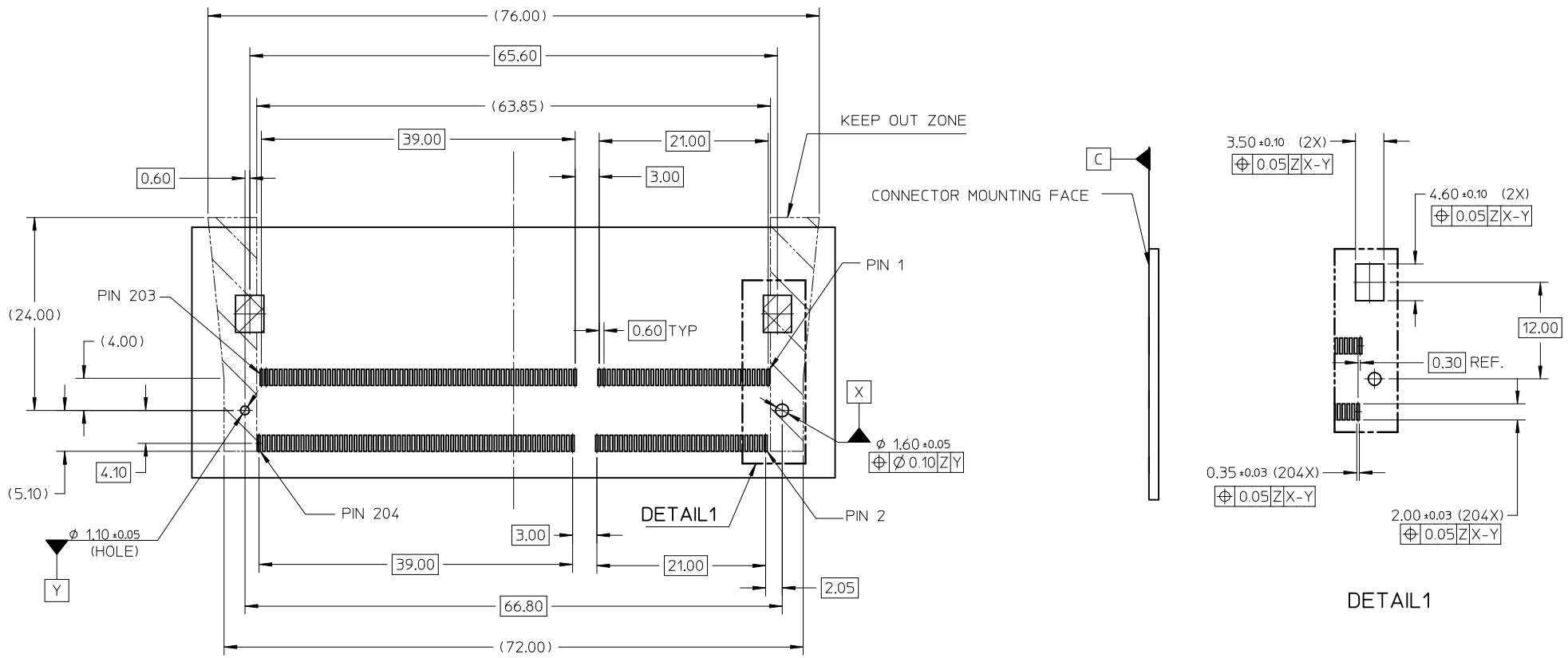
4.PRODUCT SPECIFICATION : REFER TABLE IN SHEET 6

5.PACKAGING SPECIFICATION: PART SHALL BE PACKED IN TRAY OR TAPE AND REEL.

- 6.EDGE OF CONTACT PADS SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.
- 7.THE ADDITION OF THIS BEVEL IS A FABRICATION OPTION AND IS NOT REQUIRED. THE BEVEL AIDS THE INSERTION OF THE MODULES INTO THE CONNECTOR. THE BEVEL MUST NOT ENCORACH ONTO GOLD OADS.
- 8.COPLANARITY INCLUDES HOLD DOWN 0.1 MAX.

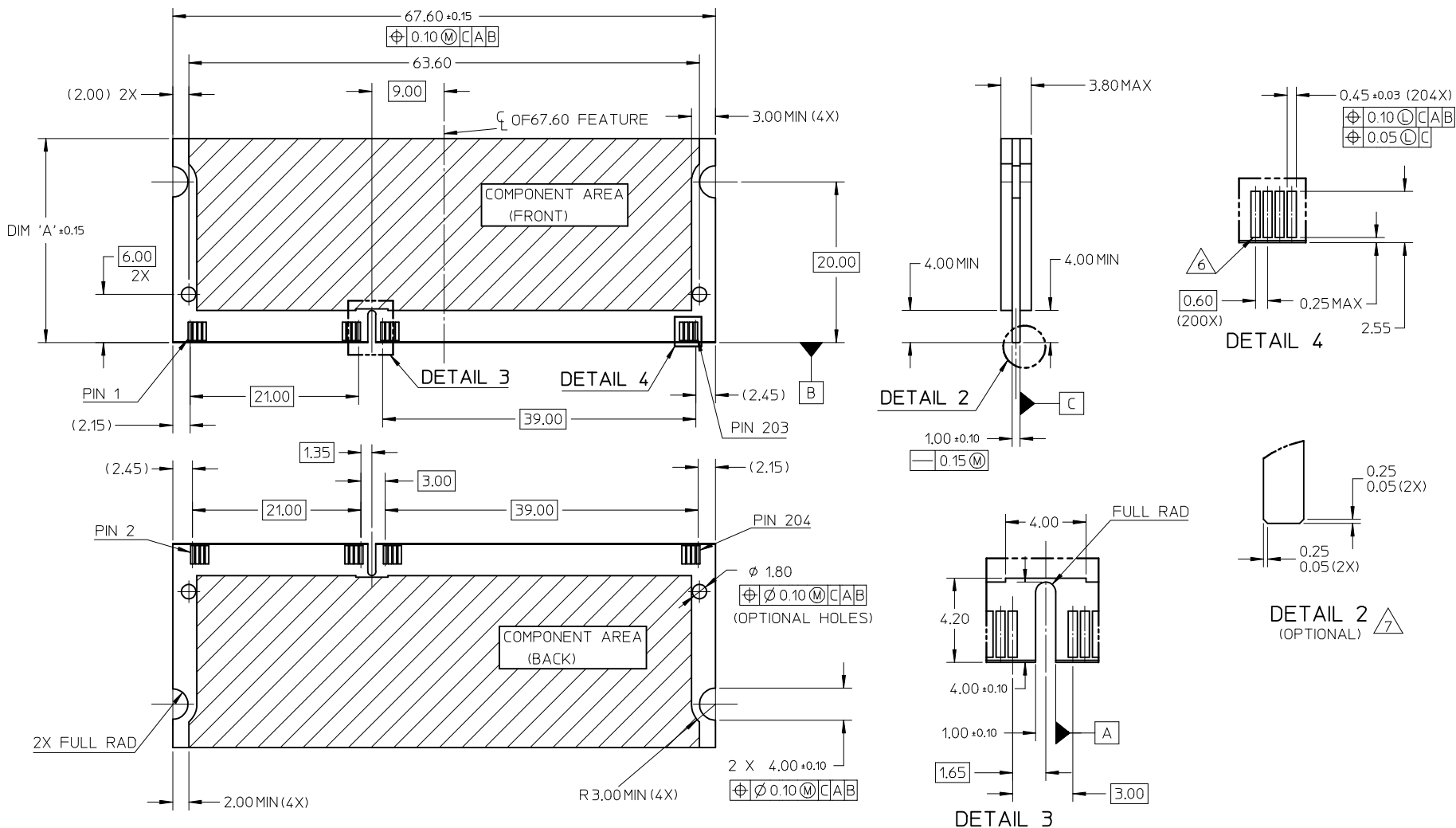
CUST REQ DIM ADD EC NO: S2010-0146 DRWN:VMANICKAM CHKD:CCTEH APPR:SHLENI	2009/08/18 2009/08/20 2009/08/20	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
					MM ONLY	NTS	METRIC			
			mm	INCH	DRAWN BY	DATE	TITLE			
			4 PLACES	± --- ± ---	CMTEO	2007/03/16	DDR3 SO DIMM			
3 PLACES	± --- ± ---	CHECKED BY	DATE	204 CKTS, 5.2MM HEIGHT						
2 PLACES	± 0.2 ± ---	VMANICKAM	2007/04/23	REVERSE ORIENTATION						
1 PLACE	± --- ± ---	APPROVED BY	DATE	MOLEX INCORPORATED						
ANGULAR ± 1 °		SHLENI	2007/04/23	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78279-001		1 OF 6				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

RECOMMENDED PCB LAYOUT



CUST REQ DIM ADD EC NO: S2010-0146 DRWN:VMANICKAM 2009/08/18 CHKD:CCTEH 2009/08/20 APPR:SHLENI 2009/08/20	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE MM ONLY DRAWN BY: CMTEO DATE: 2007/03/16 CHECKED BY: VMANICKAM DATE: 2007/04/23 APPROVED BY: SHLENI DATE: 2007/04/23	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	TITLE DDR3 SO DIMM 204 CKTS, 5.2MM HEIGHT REVERSE ORIENTATION	DOCUMENT NO. SD-78279-001	SHEET NO. 2 OF 6	
	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	REV B4	MOLEX INCORPORATED				

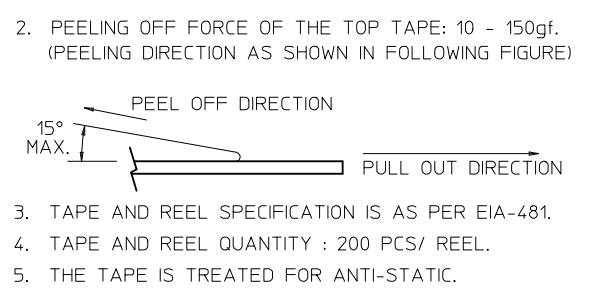
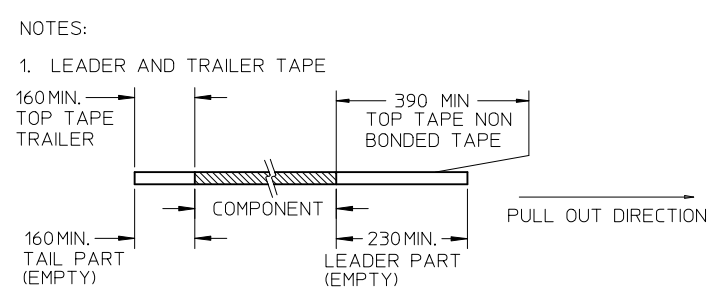
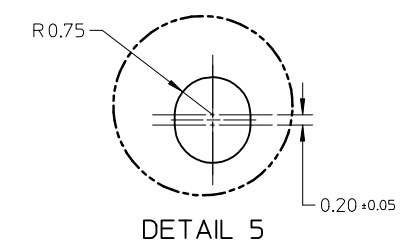
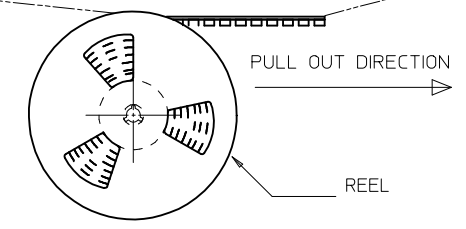
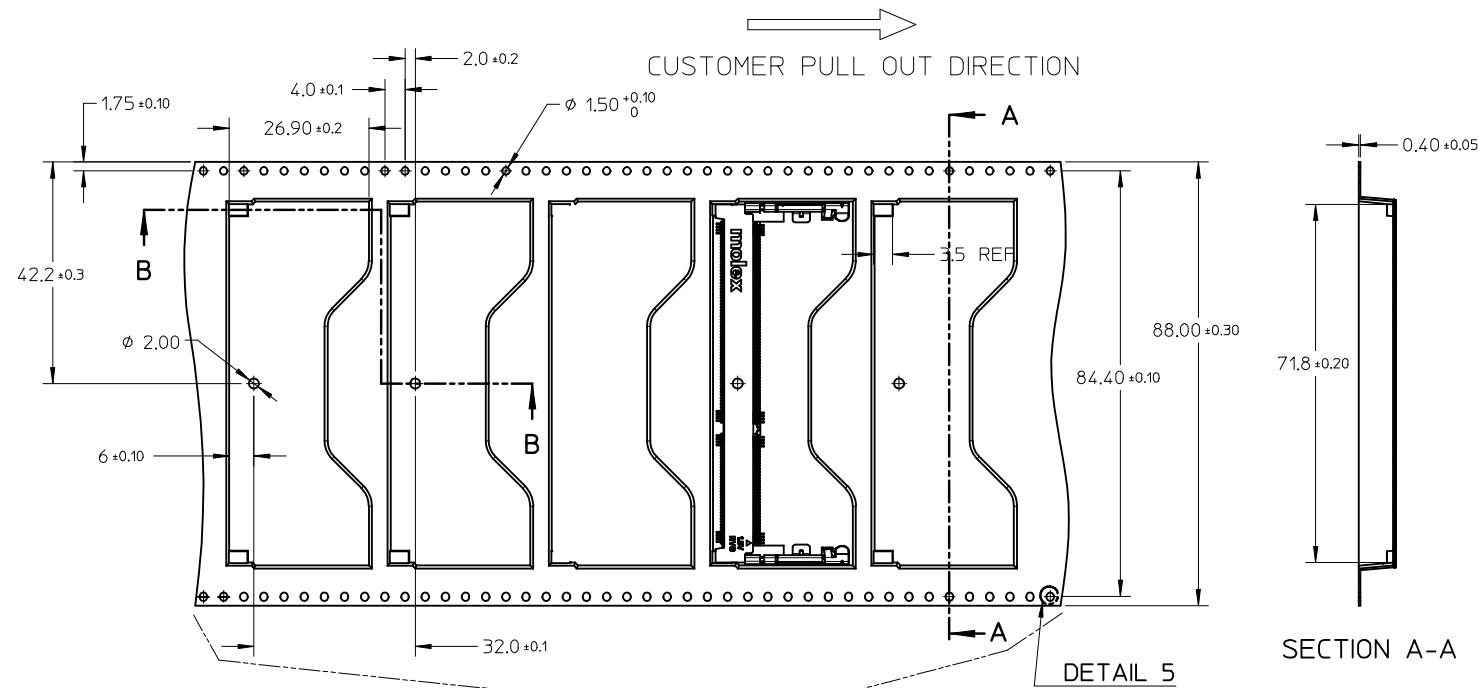
RECOMMENDED MATING PCB CONFIGURATION



SDRAM VARIATION FROM JEDEC MO-268			
	AA	BB	CC
DIM 'A'	25.40	31.75	30.00

CUST REQ DIM ADD EC NO: S2010-0146 DRWN: VMANICKAM 2009/08/18 CHKD: CCTEH 2009/08/20 APPR: SHLENI 2009/08/20	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	NTS	METRIC	
			DRAWN BY	DATE	TITLE	
			CHECKED BY	DATE		
	APPROVED BY	DATE	MOLEX INCORPORATED			
	MATERIAL NO.	SEE TABLE		DOCUMENT NO.	SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SD-78279-001 3 OF 6		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

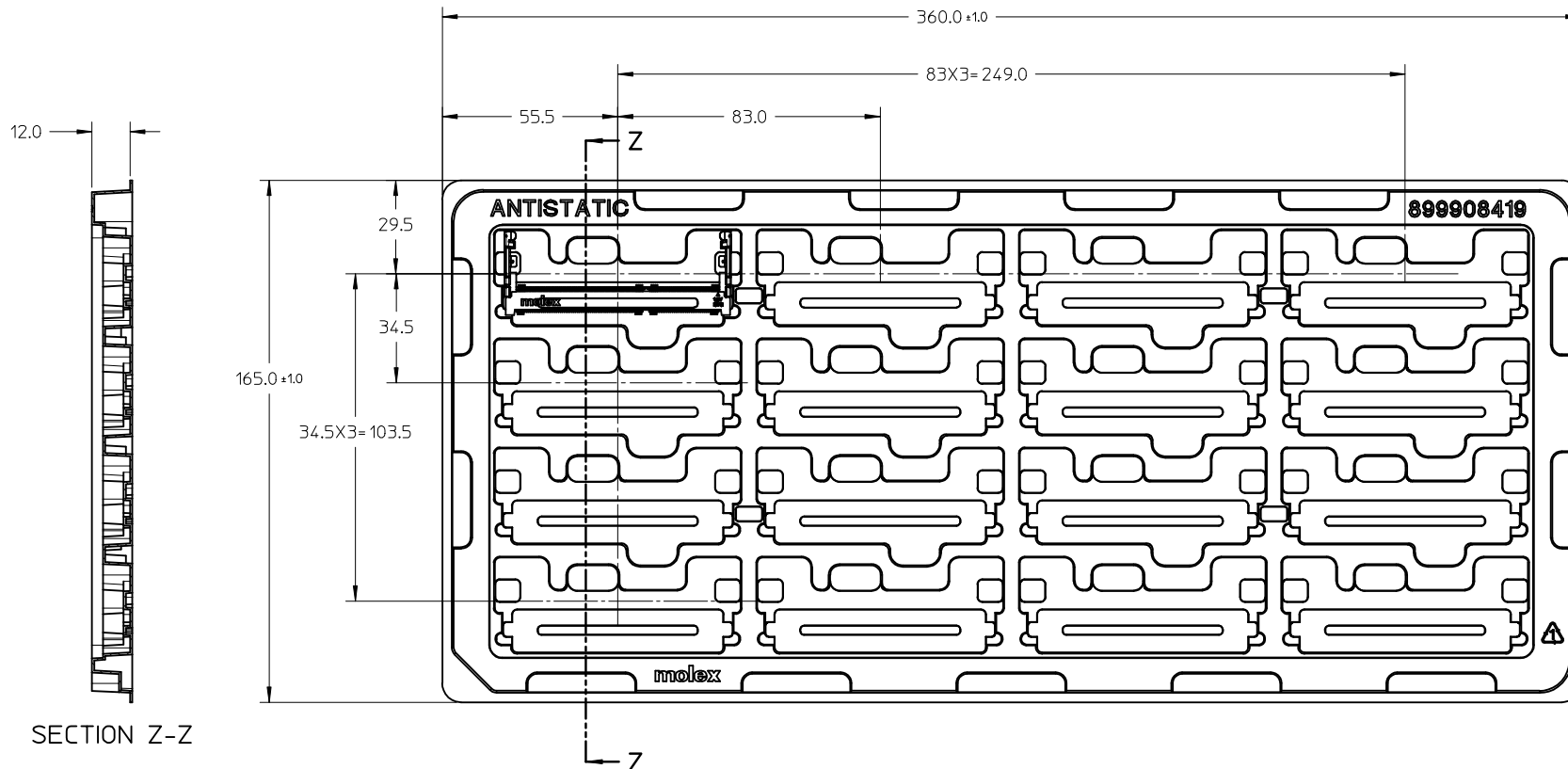
10 9 8 7 6 5 4 3 2 1



CUST REQ DIM ADD EC NO: S2010-0146 DRWN:VMANICKAM 2009/08/18 CHKD:CCTEH 2009/08/20 APPR:SHLENI 2009/08/20	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	CMTEO	2007/03/16	DDR3 SO DIMM	
			2 PLACES	± 0.2	± ---		204 CKTS, 5.2MM HEIGHT	
			1 PLACE	± ---	± ---		REVERSE ORIENTATION	
			ANGULAR ± 1 °		APPROVED BY	DATE		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHLENI	2007/04/23		
			SEE TABLE		MATERIAL NO.	DOCUMENT NO.		
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



SECTION Z-Z

NOTES:

- 1. NO OF CAVITY : 4 X 4 = 16
- 2. UNSPECIFIED TOLERANCE FOR TRAY ±0.5

CUST REQ DIM ADD EC NO: S2010-0146 DRWN:VMANICKAM 2009/08/18 CHKD:CCTEH 2009/08/20 APPR:SHLENI 2009/08/20	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		▼=0 □=0	mm	INCH	MM ONLY	NTS	METRIC			
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE			
			2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	CMTED	2007/03/16	DDR3 SO DIMM 204 CKTS, 5.2MM HEIGHT REVERSE ORIENTATION MOLEX INCORPORATED			
	ANGULAR ± 1 °		CHECKED BY	DATE	DOCUMENT NO.					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	SD-78279-001		5 OF 6	
					SHLENI	2007/04/23				
					MATERIAL NO.	SEE TABLE				
					SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
					A3					

9 8 7 6 5 4 3 2 1

PART NO	CONTACT AREA FINISH	SOLDER TAIL FINISH	PACKAGING	PRODUCT SPECIFICATION
78279-0001	3μN GOLD OVER 50μN/1.27μM NICKEL	100 MICROINCH /2.54 MICROMETER MATTE TIN OVER 50 MICEOINCH / 1.27 MICROMETER.	TRAY (360X165MM)	PS-78279-003
78279-1501	15μN/0.38μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-002
78279-3001	30μN/0.76μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-001
78279-0002	3μN GOLD OVER 50μN/1.27μM NICKEL	GOLD FLASH OVER 50μN/1.27μM NICKEL.		PS-78279-003
78279-1502	15μN/0.38μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-002
78279-3002	30μN/0.76μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-001
78279-0011	3μN GOLD OVER 50μN/1.27μM NICKEL	100 MICROINCH /2.54 MICROMETER MATTE TIN OVER 50 MICEOINCH / 1.27 MICROMETER.	TAPE&REEL	PS-78279-003
78279-1511	15μN/0.38μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-002
78279-3011	30μN/0.76μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-001
78279-0012	3μN GOLD OVER 50μN/1.27μM NICKEL	GOLD FLASH OVER 50μN/1.27μM NICKEL.		PS-78279-003
78279-1512	15μN/0.38μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-002
78279-3012	30μN/0.76μM GOLD OVER 50μN/1.27μM NICKEL			PS-78279-001

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	▼=0 □=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DRAWN BY DATE CMTEO 2007/03/16 CHECKED BY DATE VMANICKAM 2007/04/23 APPROVED BY DATE SHLENI 2007/04/23	TITLE DDR3 SO DIMM 204 CKTS, 5.2MM HEIGHT REVERSE ORIENTATION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	MOLEX INCORPORATED		SHEET NO. 6 OF 6
	B4			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	